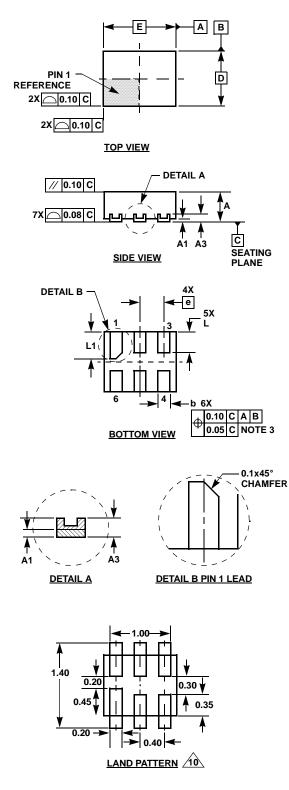
Ultra Thin Dual Flat No-Lead Plastic Package (UTDFN)



L6.1.2x1.0A

6 LEAD ULTRA THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE

	MILLIMETERS			
SYMBOL	MIN	NOMINAL	MAX	NOTES
А	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3	0.127 REF			-
b	0.15	0.20	0.25	5
D	0.95	1.00	1.05	-
E	1.15	1.20	1.25	-
е	0.40 BSC			-
L	0.30	0.35	0.40	-
L1	0.40	0.45	0.50	-
Ν	6			2
Ne	3			3
θ	0	-	12	4

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.

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- 2. N is the number of terminals.
- 3. Ne refers to the number of terminals on E side.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Maximum package warpage is 0.05mm.
- 8. Maximum allowable burrs is 0.076mm in all directions.
- 9. JEDEC Reference MO-255.
- 10. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.